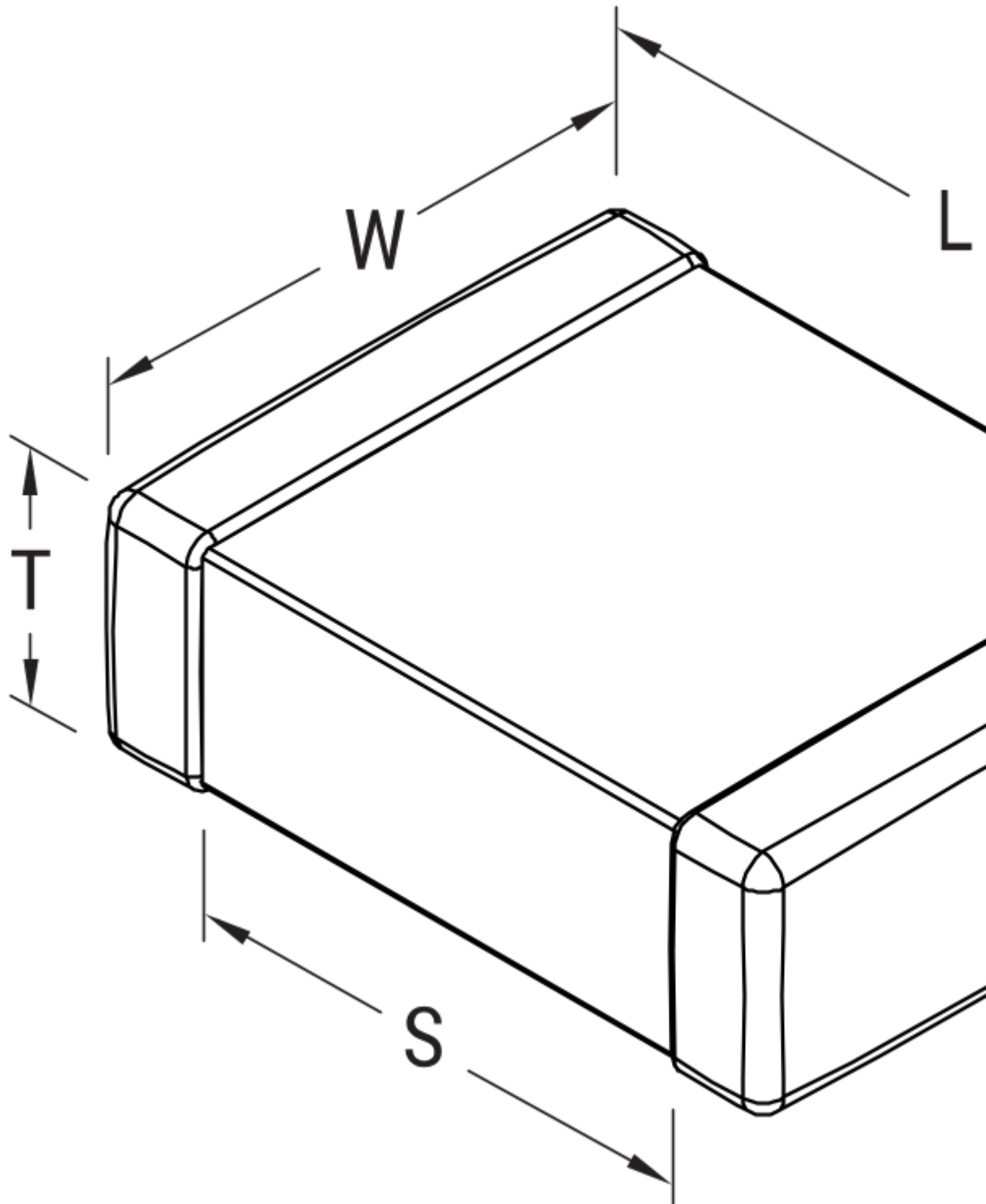


C0805C332F1GECTU

Aliases (C0805C332F1GEC7800)

ESD SMD Comm C0G, Ceramic, 3300 pF, 1%, 100 VDC, C0G, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 0805



Click [here](#) for the 3D model.

Dimensions

Chip Size 0805

L 2mm +/-0.2mm

Dimensions

W	1.25mm +/-0.2mm
T	0.78mm +/-0.10mm
S	0.75mm MIN
B	0.5mm +/-0.25mm

Packaging Specifications

Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	4000

General Information

Series	ESD SMD Comm C0G
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	11 mg
Shelf Life	78 Weeks
MSL	1

Specifications

Capacitance	3300 pF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	1%
Voltage DC	100 VDC
ESD Level per AEC-Q200	16,000 V ESD Level
Dielectric Withstanding Voltage	250 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	C0G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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